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General Description

- The AO6404 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V while retaining a 12V $V_{GS(MAX)}$ rating.
- RoHS and Halogen-Free Compliant

Product Summary

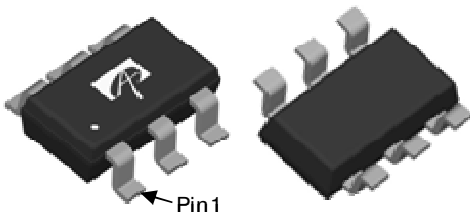
$V_{DS} (V) = 20V$
 $I_D = 8.6A (V_{GS} = 10V)$
 $R_{DS(ON)} < 17m\Omega (V_{GS} = 10V)$
 $R_{DS(ON)} < 18m\Omega (V_{GS} = 4.5V)$
 $R_{DS(ON)} < 24m\Omega (V_{GS} = 2.5V)$
 $R_{DS(ON)} < 33m\Omega (V_{GS} = 1.8V)$

ESD Rating: 2000V HBM

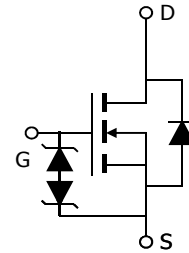
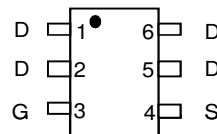
ESD Protected
 100% UIS Tested
 100% Rg Tested



Top View Bottom View



Top View



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AO6404	TSOP6	Tape & Reel	3000

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^A	$T_A=25^\circ C$	8.6	A
	$T_A=70^\circ C$	6.8	
Pulsed Drain Current ^B	I_{DM}	30	
Power Dissipation ^A	$T_A=25^\circ C$	2	W
	$T_A=70^\circ C$	1.28	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	45	62.5	$^\circ C/W$
Maximum Junction-to-Ambient ^A		Steady-State	70	110
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	33	50	$^\circ C/W$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =16V, V _{GS} =0V T _J =55°C			10 25	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±10V			10	μA
BV _{GSO}	Gate-Source Breakdown Voltage	V _{DS} =0V, I _G =±250μA	±12			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	0.5	0.75	1	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	30			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =8.5A T _J =125°C		13.4	17	mΩ
		V _{GS} =4.5V, I _D =5A		14.8	18	
		V _{GS} =2.5V, I _D =4A		18.8	24	mΩ
		V _{GS} =1.8V, I _D =3A		25.5	33	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =8A		36		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.73	1	V
I _S	Maximum Body-Diode Continuous Current				2.9	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, f=1MHz		1810	2200	pF
C _{oss}	Output Capacitance			232		pF
C _{rss}	Reverse Transfer Capacitance			200		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		1.6	2.2	Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =8.5A		17.9	22	nC
Q _{gs}	Gate Source Charge			1.5		nC
Q _{gd}	Gate Drain Charge			4.7		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =10V, R _L =1.2Ω, R _{GEN} =3Ω		2.5		ns
t _r	Turn-On Rise Time			7.2		ns
t _{D(off)}	Turn-Off DelayTime			49		ns
t _f	Turn-Off Fall Time			10.8		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =8.5A, di/dt=100A/μs		22	27	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =8.5A, di/dt=100A/μs		9.8		nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

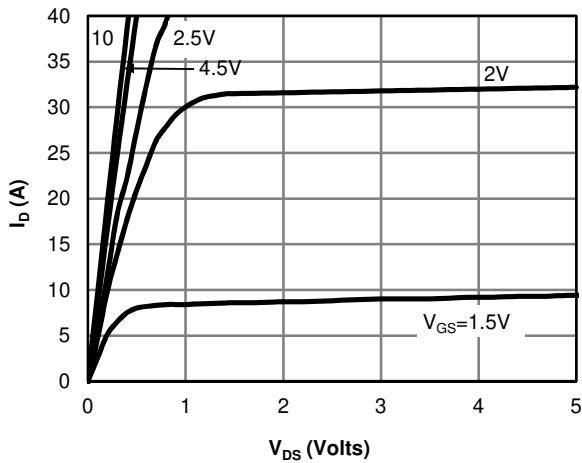


Fig 1: On-Region Characteristics

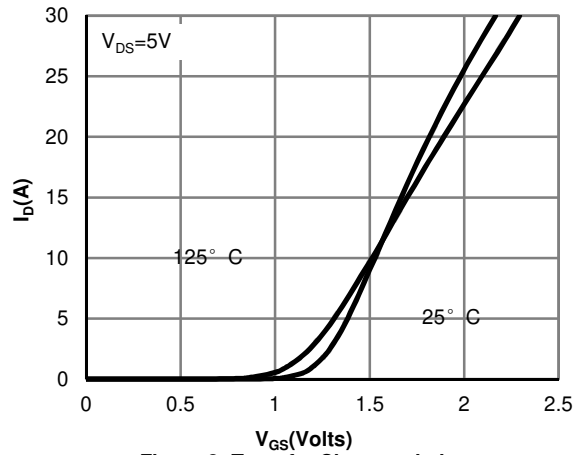


Figure 2: Transfer Characteristics

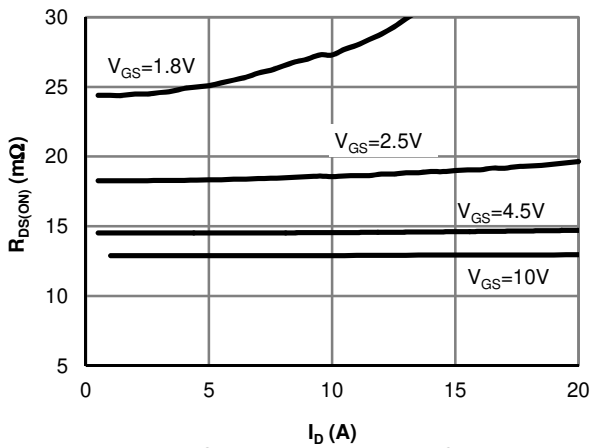


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

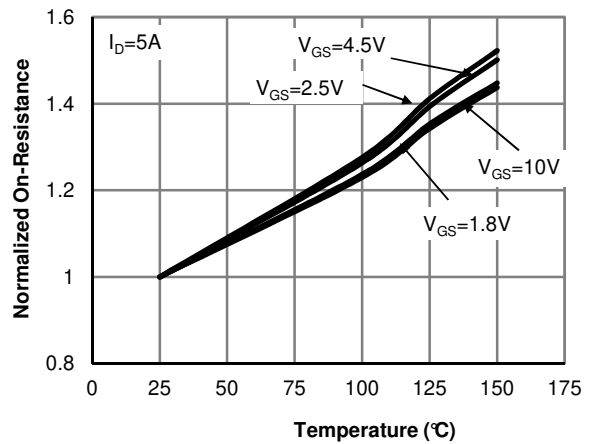


Figure 4: On-Resistance vs. Junction Temperature

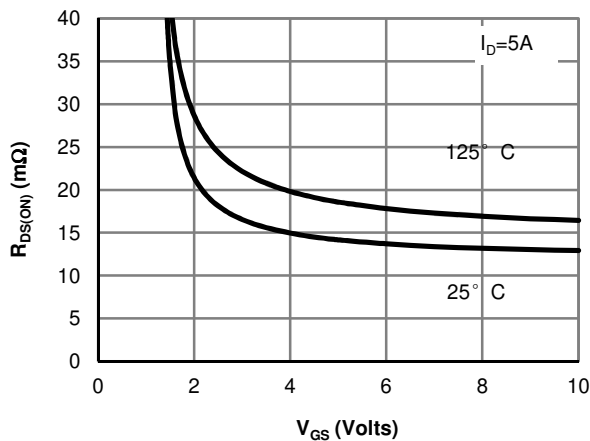


Figure 5: On-Resistance vs. Gate-Source Voltage

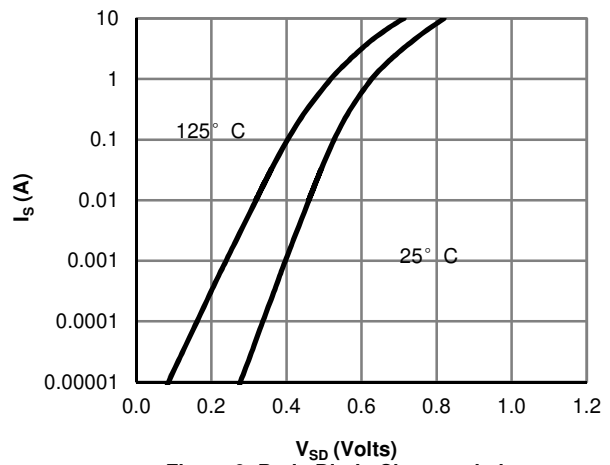


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

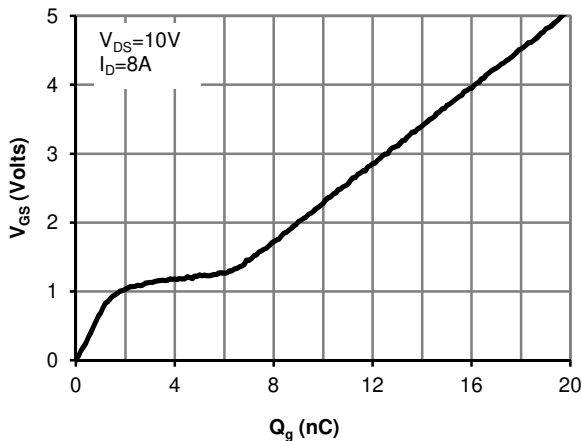


Figure 7: Gate-Charge Characteristics

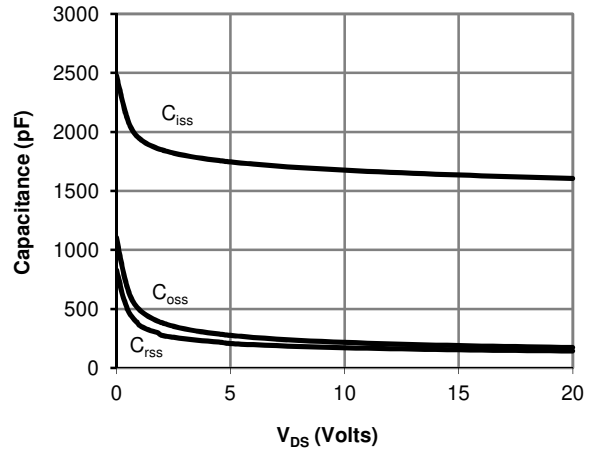


Figure 8: Capacitance Characteristics

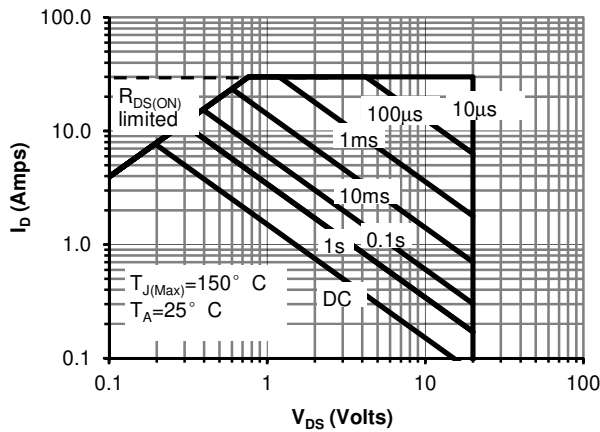


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

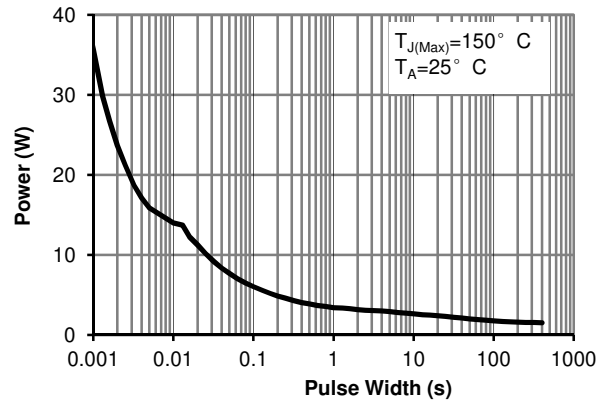


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

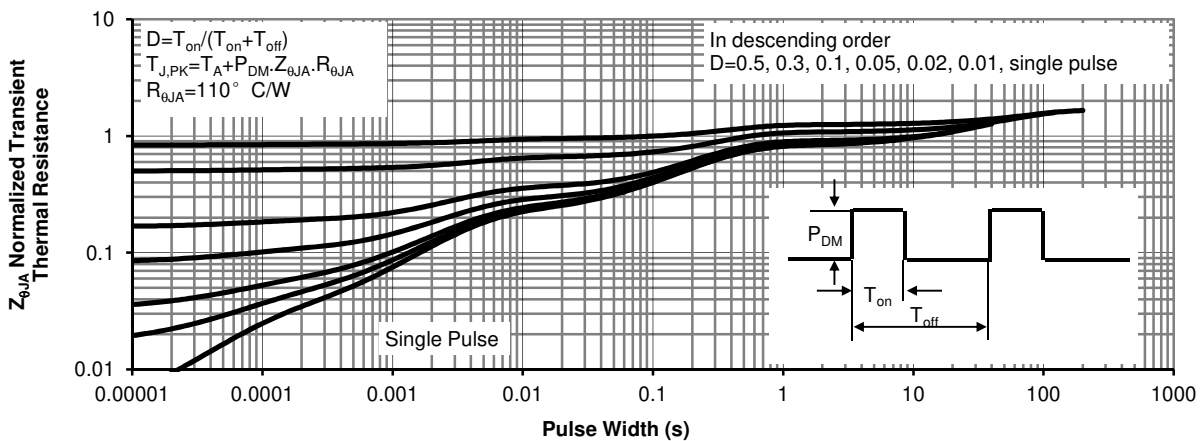


Figure 11: Normalized Maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit & Waveforms

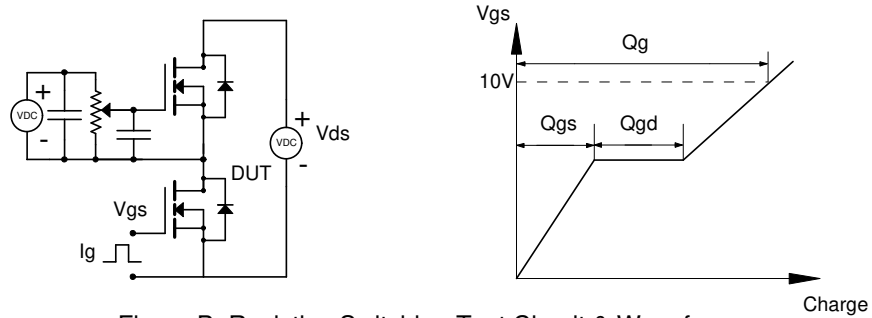


Figure B: Resistive Switching Test Circuit & Waveforms

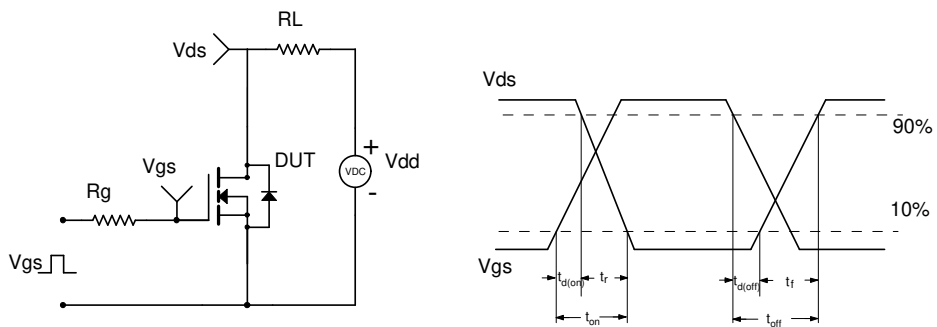


Figure C: Unclamped Inductive Switching (UIS) Test Circuit &

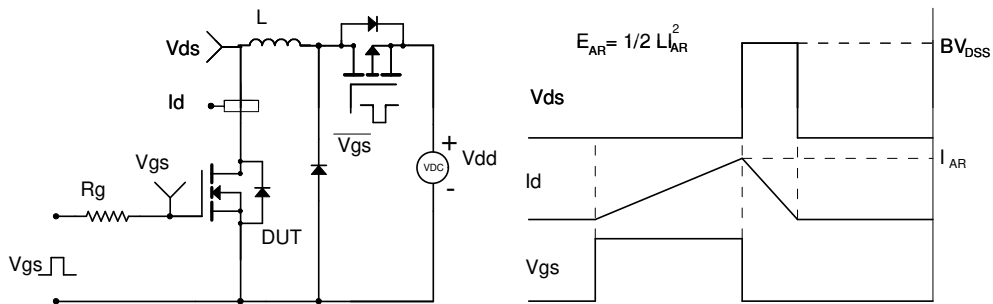


Figure D: Diode Recovery Test Circuit & Waveforms

